

EMV Compliant

TECHNICAL CHARACTERISTICS

1. General Characteristics

Dimension: 55.50L x 40.00W x 5.80H mm

Weight: Approx. 12.55 g

Contact principle: Landing technology

Operating position: Shaft up / Down / Horizontal

Mounting System: DIP or SMT Type (with post)

Durability: 500,000 cycles min.

2. Mechanical Characteristics

Insulation material: Thermoplastic, UL 94V-0

RoHS Directive 2011/65/EU Compliant

3. Electrical Characteristics

Number of contacts: 8 pins

Contact resistance: 50 mΩ typical, 100 mΩ max.

Insulation resistance: >1000 MΩ / 500 VDC

Switch type: Sealed

Operation: Normally Open

4. Solderability

Wave: 260°C, 5 sec. Max.

IR reflow: Not applicable

Manual soldering: 360°C, 3 sec. Max.

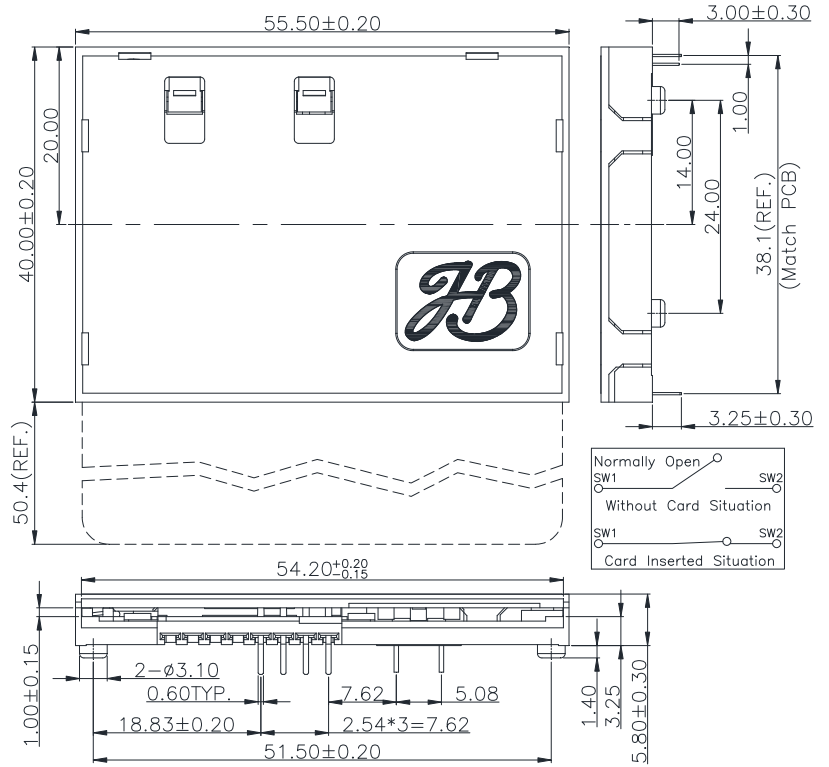
5. Environmental Characteristics

Operating temperature: - 40°C ~ + 85°C

Operating humidity: 10 % ~ 95 % RH

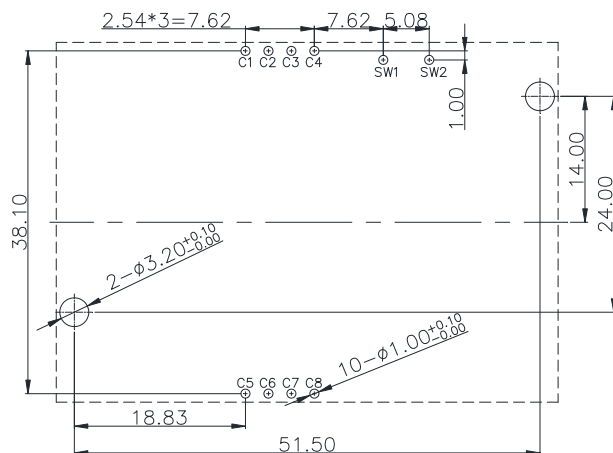
Storage temperature: - 40°C ~ + 85°C

Storage humidity: 10 % ~ 95 % RH



Unit: mm; Tolerances: ±0.15 mm

Mechanical outline dimension



Unit: mm; Tolerances: ±0.05 mm

Reference dimension for PCB layout

HB Smart Card Acceptor

Model No.: ICA-705 DIP

Revision: 1.6

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For further information, please contact:

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